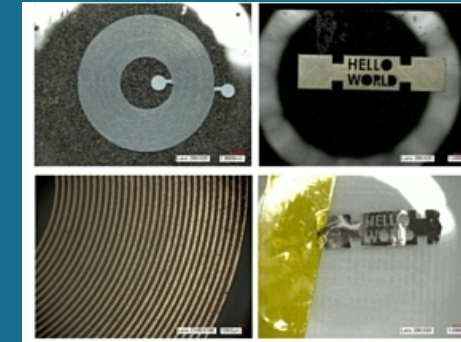




# Assessing Aerosol Jet Printed Gold Inks for Printed Electronics Applications



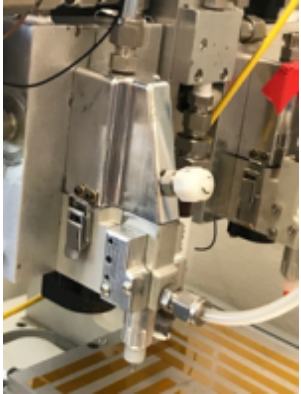
Yongkun Sui, Lok-kun Tsui, Chowdary R. Koripella, Andrew Sanford, and Judith M. Lavin

7/25/2022

Solid-freeform Fabrication Symposium

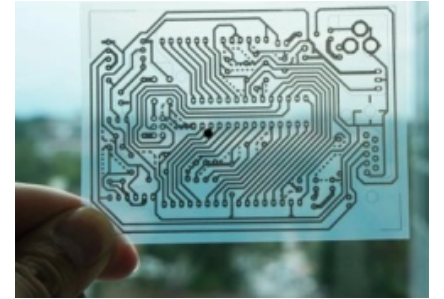


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Brief overview of aerosol-jet printing

Applications of printed gold



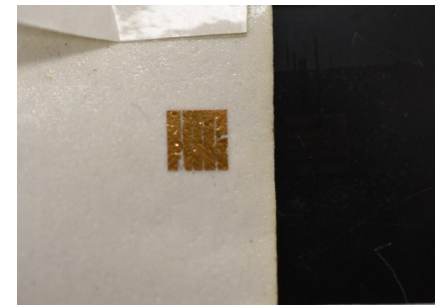
Printing quality optimization

Thermal sintering

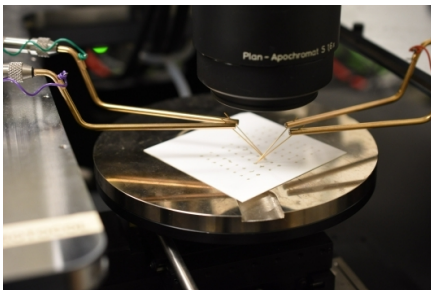
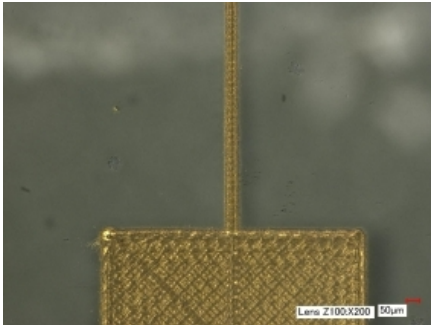


Conductivity measurement

Adhesion test



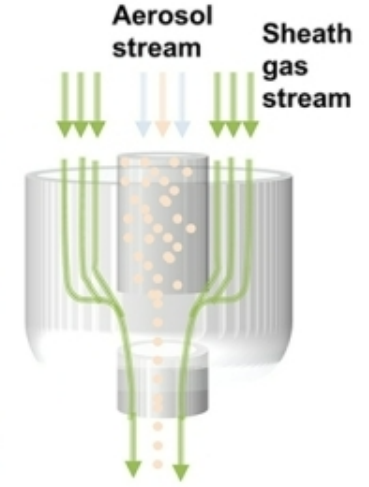
Summary and conclusion



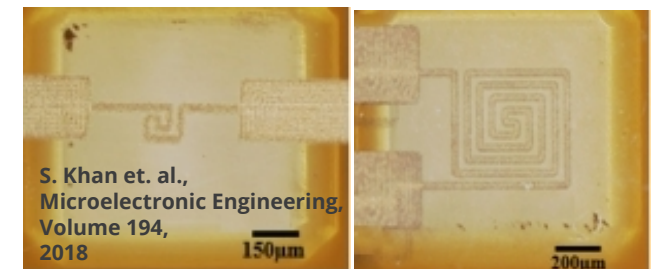
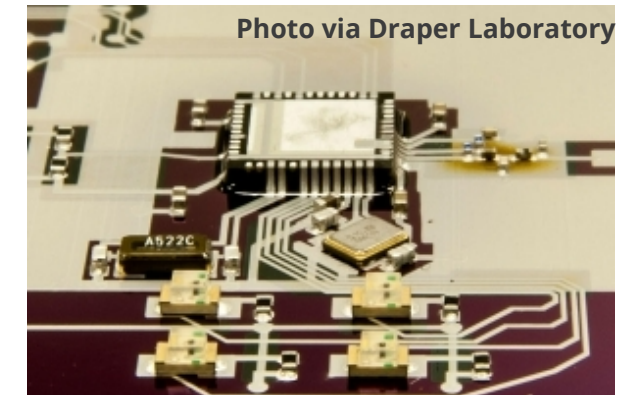
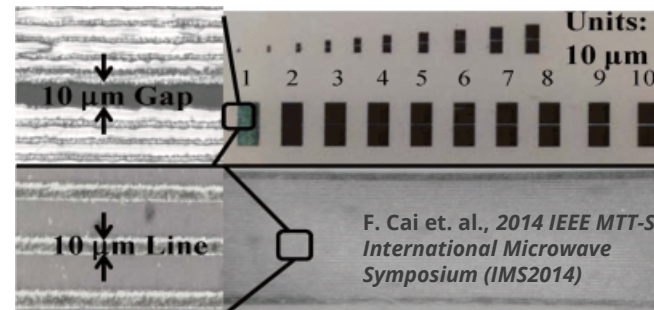
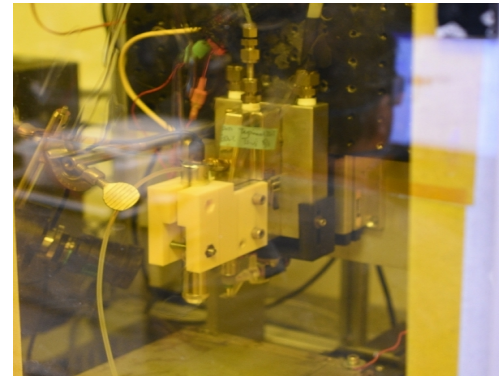
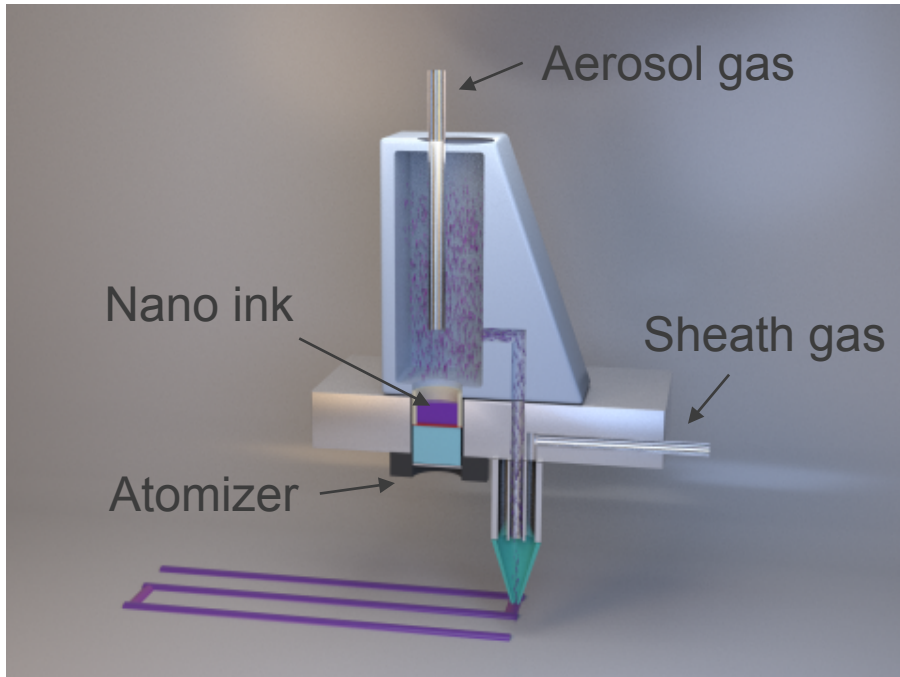


# What is Aerosol-Jet Printing?

- Use **aerodynamic focusing** to precisely and accurately deposit electronic inks onto substrates
- The ink is placed into a vial; ink mist generated through **ultrasonic atomization**
- The aerosol mist is then carried by the **aerosol gas** to the print head where it is focused by a **sheath gas**
- Advantages: high-resolution, non-contact, rapid-prototyping



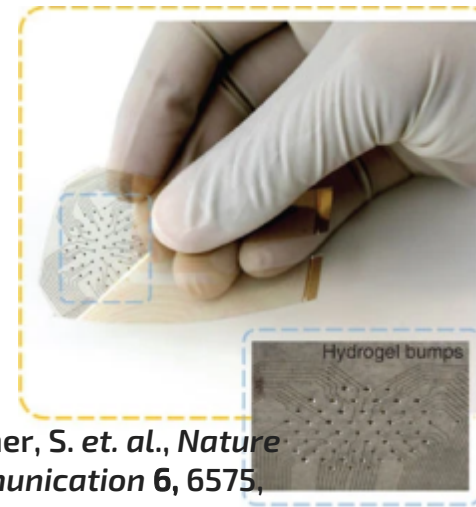
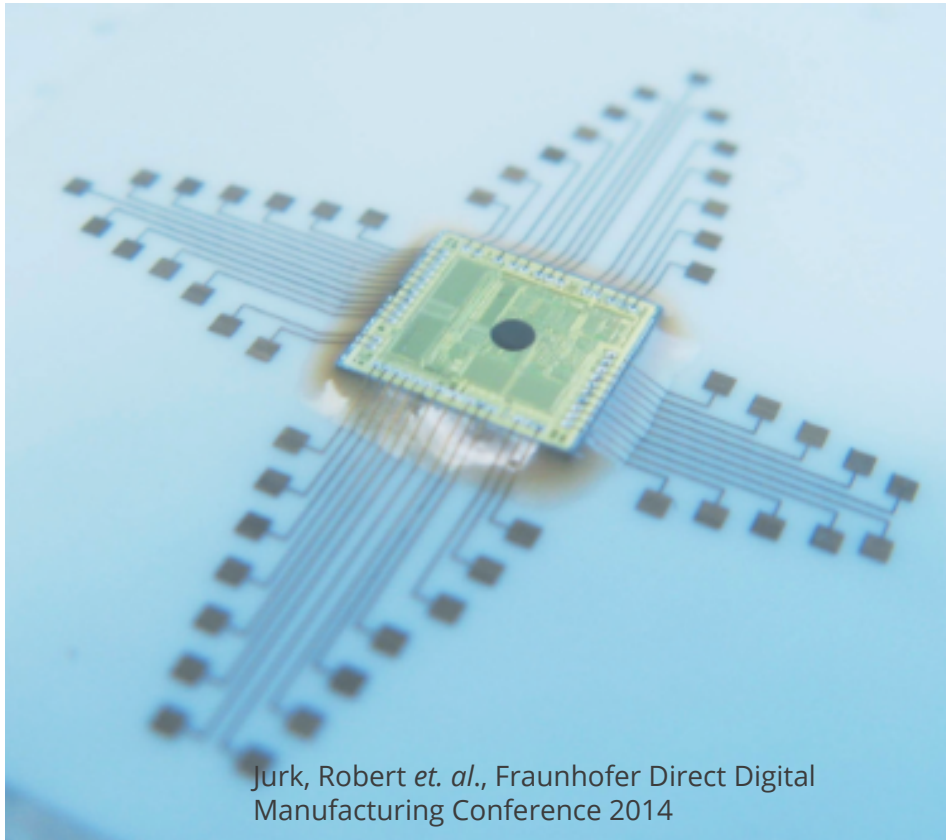
MAS.865 2018 How to Make Something that Makes (almost) Anything, MIT



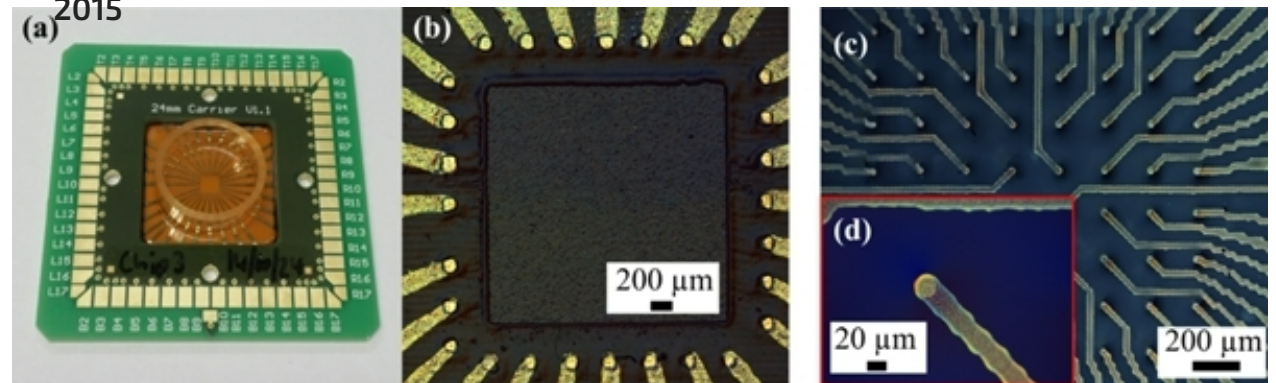
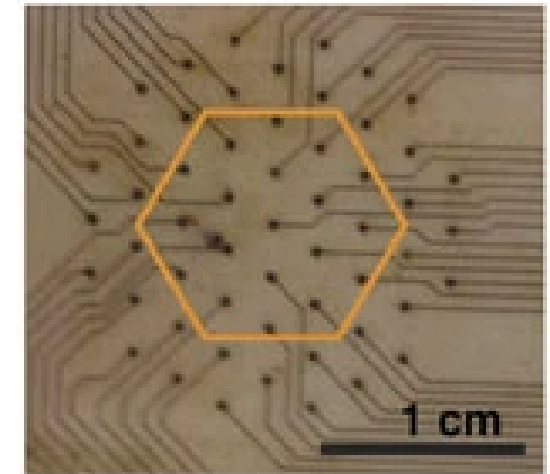
# Printed Gold Applications



- Silver is the most popular material for printed electronics
- Advantages of gold compared to silver
  - **Chemical inertness**, more suitable for harsh environment applications
  - **Biocompatibility**, medical applications



Swisher, S. *et. al.*, *Nature Communication* 6, 6575, 2015

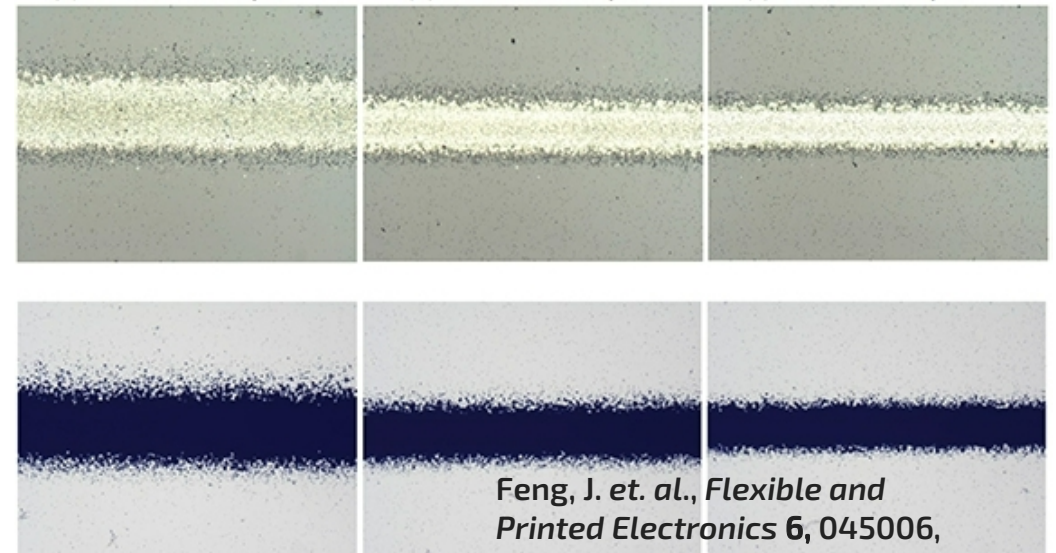


Bachmann *et. al.*, *Flexible and Printed Electronics*, 2017

	UTDots Au40X	UTDots Au25X	NovaCentrix 25% Au
Solvent	Xylenes	Xylenes	Water
Loading (w/v)	40%	25%	25%
Dilution (v/v)	ink:xylenes:terpineol = 2:2:1	ink:xylenes:terpineol = 10:2:1	ink:water = 2:1
Loading after dilution	16.0%	19.2%	16.7%

Parameters to consider:

- Line and infill resolution
- Overspray
- Conductivity
- Stability
- Adhesion (ASTM D3359-17)



Feng, J. et. al., *Flexible and Printed Electronics* 6, 045006, 2021



# Optimizing Print Quality

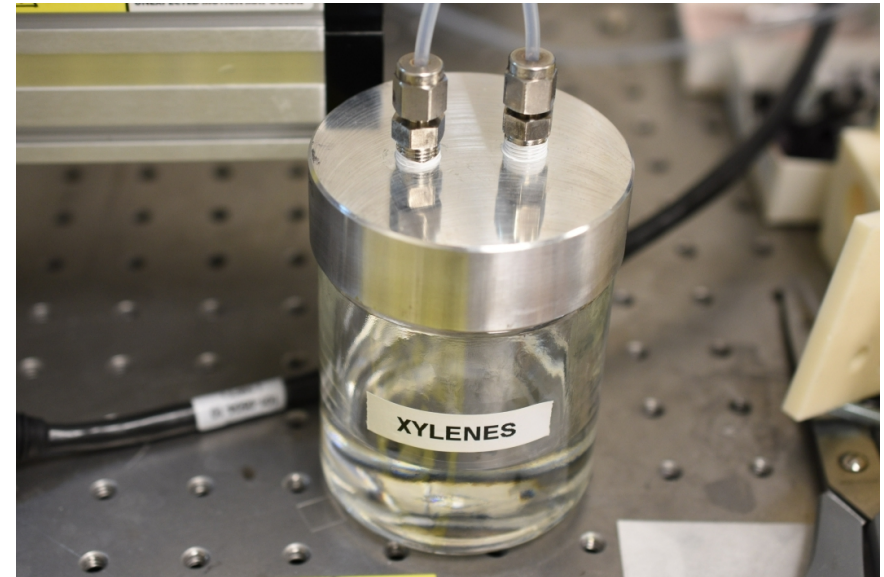


Three main parameters to tune:

- Atomization voltage
- Aerosol gas flow rate
- Sheath gas flow rate

Fixed parameters:

- Printing platen temperature - 100 °C
- Printing speed - 300 mm/min
- Number of layers - 4 layers
- Nozzle orifice - 150  $\mu\text{m}$  (Fisnar)
- Vapor jar
  - Xylenes for the xylenes-based inks
  - DI water for the water-based ink



# Line and Pad Quality as a Function of Focusing Ratio



Focusing Ratio (FR)  
= SG/AG

**UTDots Au25X, atomization voltage (AV) = 35 V**

SG = 20 SCCM

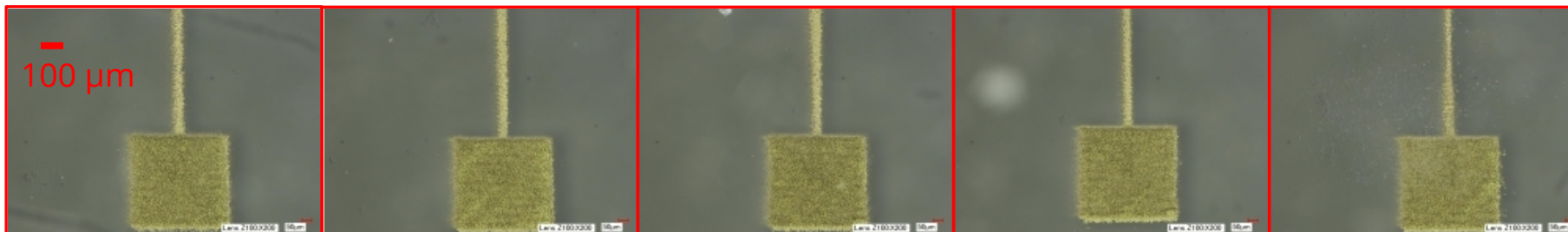
SG = 25 SCCM

SG = 30 SCCM

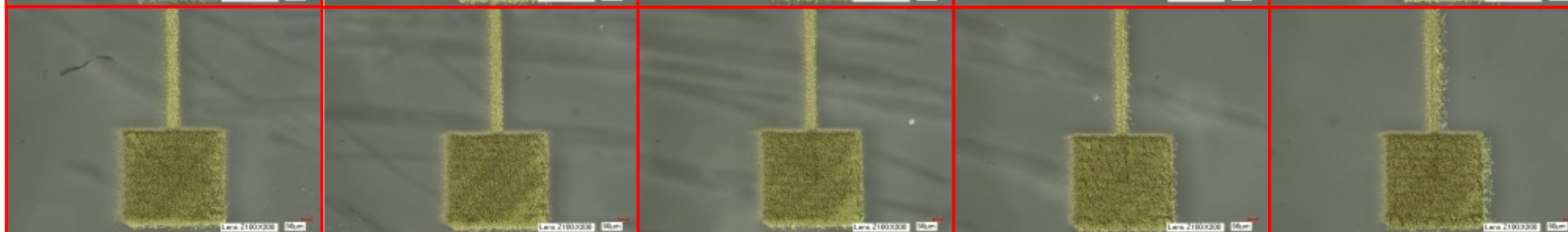
SG = 35 SCCM

SG = 40 SCCM

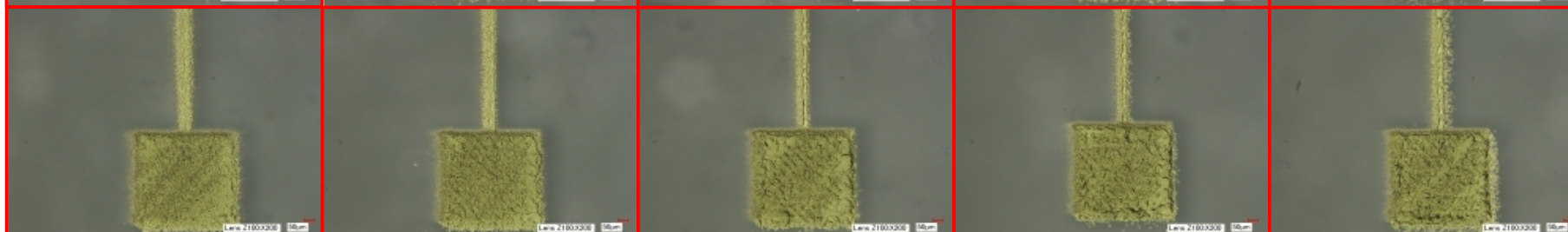
AG = 3 SCCM



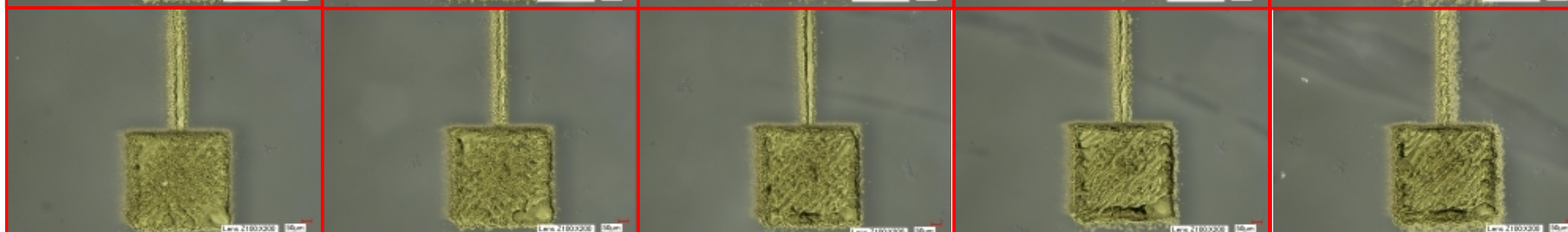
AG = 3.5 SCCM



AG = 4 SCCM



AG = 4.5 SCCM

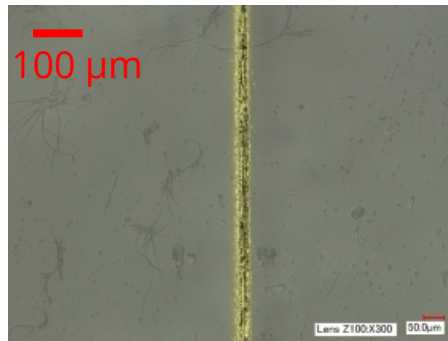


# Line and Pad Quality with Optimized Print Conditions

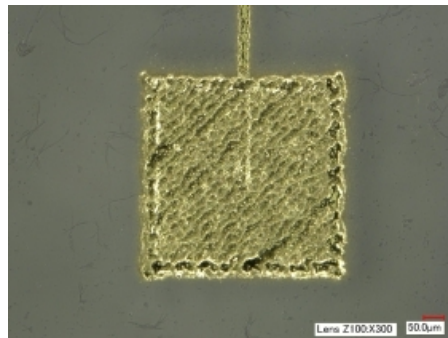


	AG range (SCCM)	SG range (SCCM)	AV range (V)
UTDots Au 40X	3-5	20-40	20
UTDots Au 25X	3-4.5	20-40	34-37
NC 25% Au	3-4	25-35	18.5-23.5

UTDots Au40X



- AG 3 SG 25  
AV 20
- Slight overspray

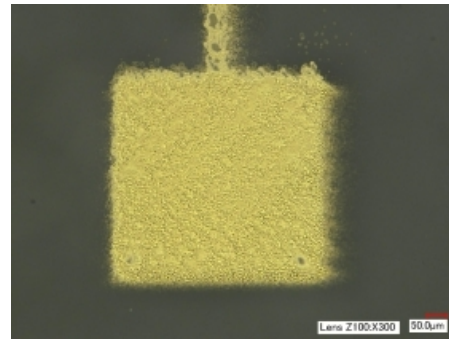
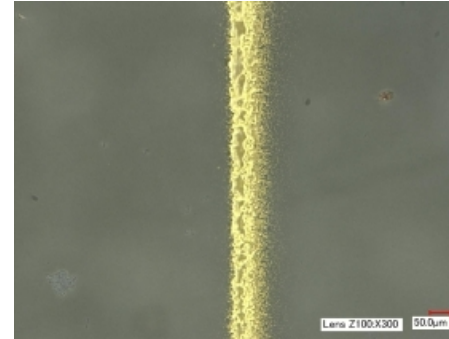


- Moderate overspray
- Rough texture

- AG 4 SG 25  
AV 35
- Severe overspray
- Line spreading

- Severe overspray

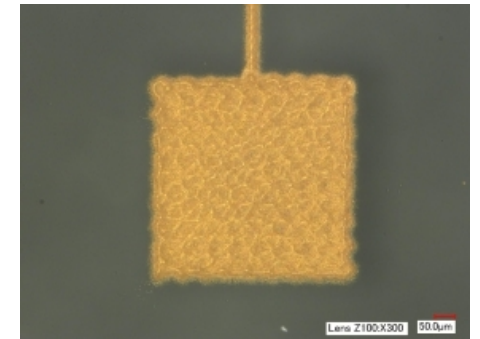
UTDots Au25X



- AG 4 SG 35  
AV 23.5
- Slight overspray

- Slight overspray
- Smooth texture

NC 25% Au



	UTDots Au 40X	UTDots Au 25X	NC Au 25%
Line quality	+	-	+
Pad quality	+	-	++



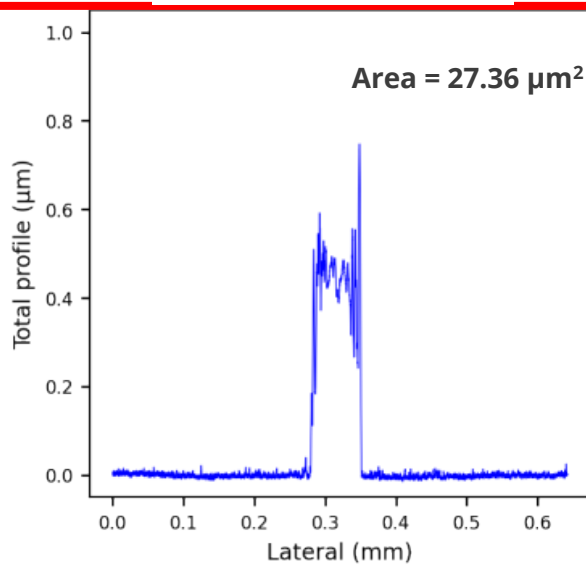
# Profilometry



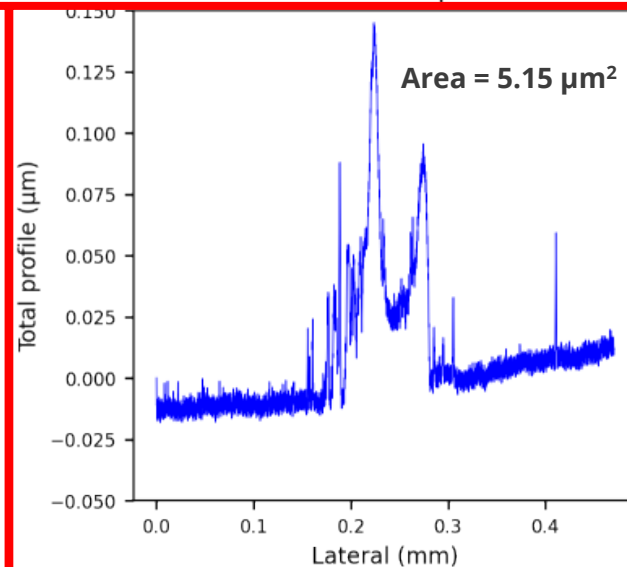
- Stylus profilometer (Bruker Dektak)
- 3 spots per line and 3 lines measured for each ink

	UTDots Au40X	UTDots Au25X	NC 25% Au
Avg. area ( $\mu\text{m}^2$ )	27.1	5.2	19.1
Std. dev. Area ( $\mu\text{m}^2$ )	1.2	0.3	5.8

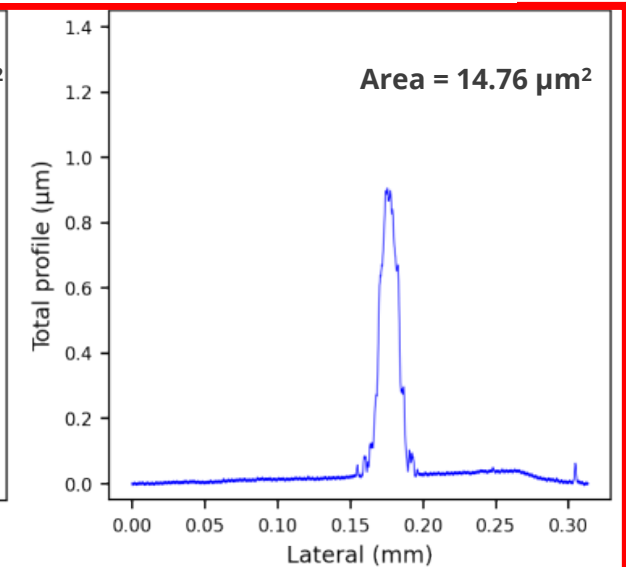
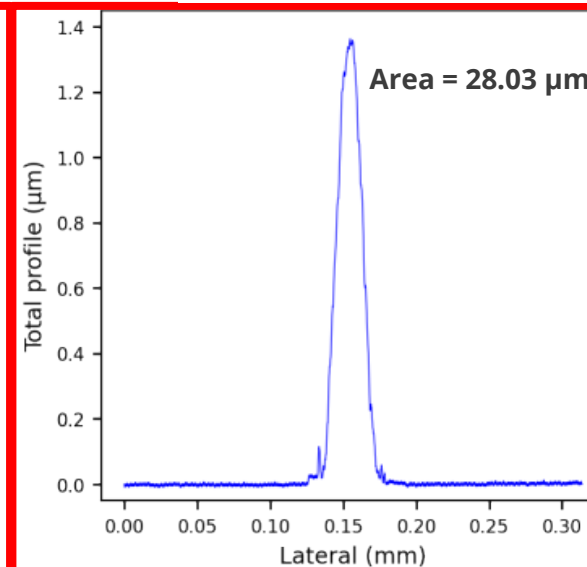
UTDots Au40X



UTDots Au25X



NC 25% Au

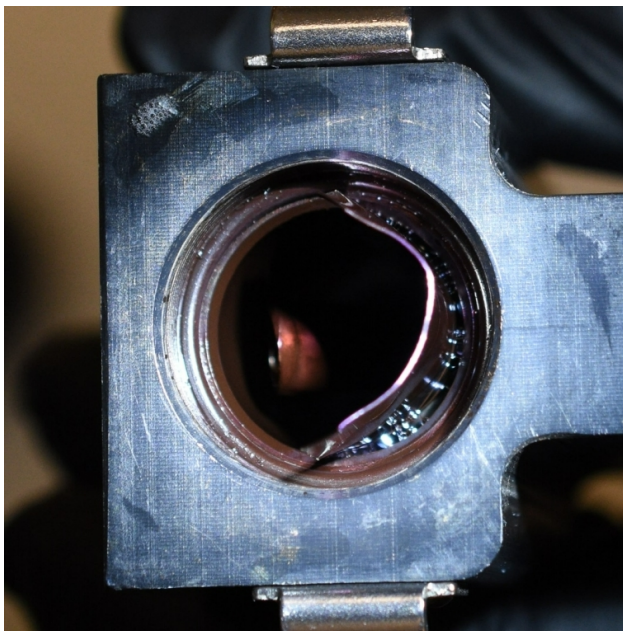


# Ink Stability



- NC 25% Au has a low surface tension and foams after 10-15 min of continuous atomization
- UTDots Au25X was atomized at 35 V, which may have some instability issue

PEEK cartridge



Ink vial



Metal cartridge

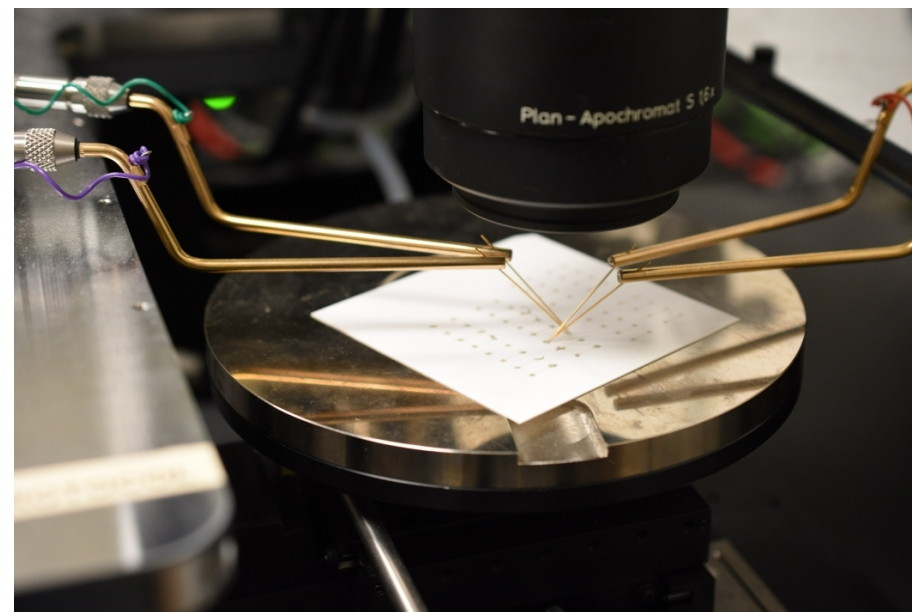


	UTDots Au 40X	UTDots Au 25X	NC Au 25%
Atomization stability	++	+	-

# Electrical Conductivity Measurements



- Inks were thermally sintered 1 °C /min from ambient temperature to 300 °C, held at 300 °C for 3 hours, then cooled to ambient temperature
- Test setup: Keithley 2400 source meter; 4-wire connection; sourcing I and measuring V
- Silver epoxy applied to the gold pads, cured at 100 °C for 1 hour
- 4 mm lines



	UTDots Au40X	UTDots Au25X	NC Au 25%
Avg. Resistance ( $\Omega$ )	10.4	90.4	16.4
Std. dev. Resistance ( $\Omega$ )	0.5	9.0	4.5
Resistivity ( $m\Omega \cdot \mu m$ )	71.5	128.8	78.3
x bulk Au resistivity	3.3 x	5.8 x	3.6 x
<b>% bulk Au conductivity</b>	<b>30.8%</b>	<b>17.1%</b>	<b>28.1%</b>



# Performance Comparison

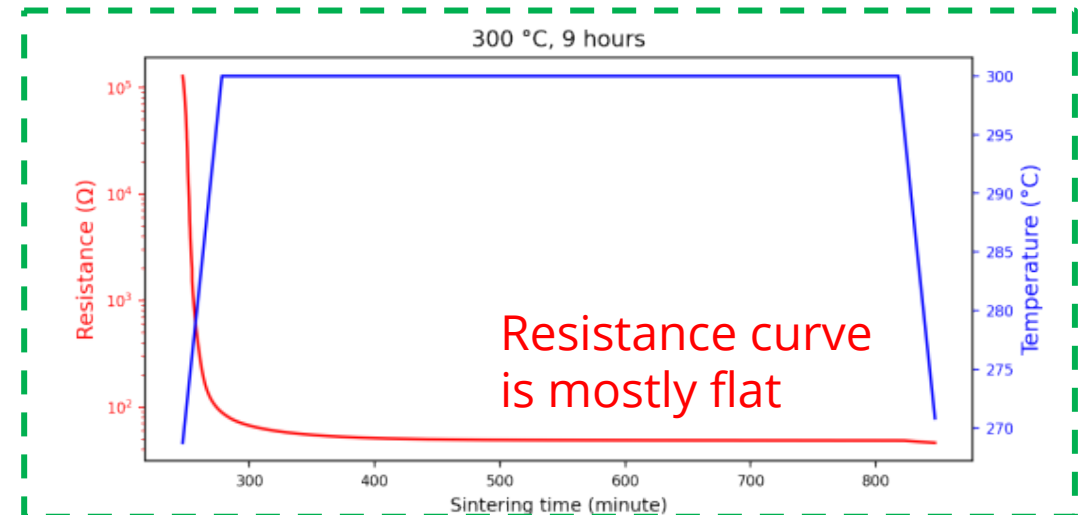
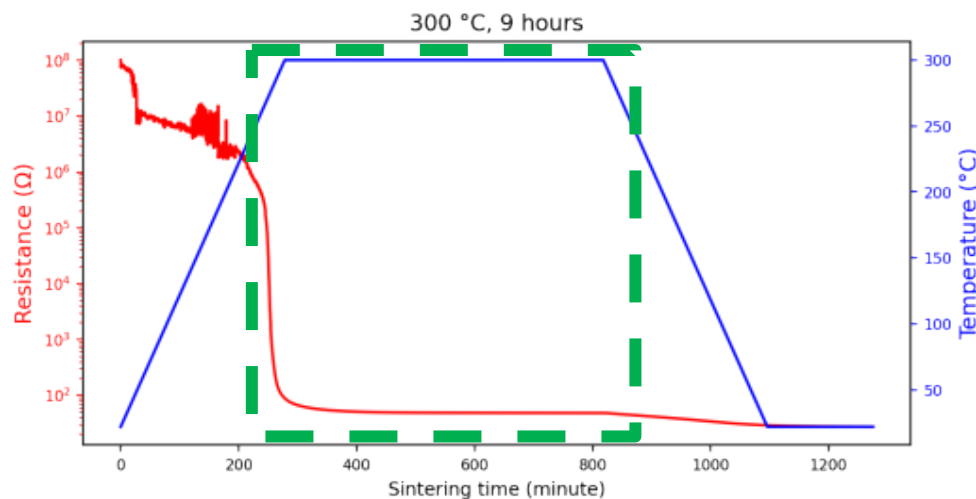
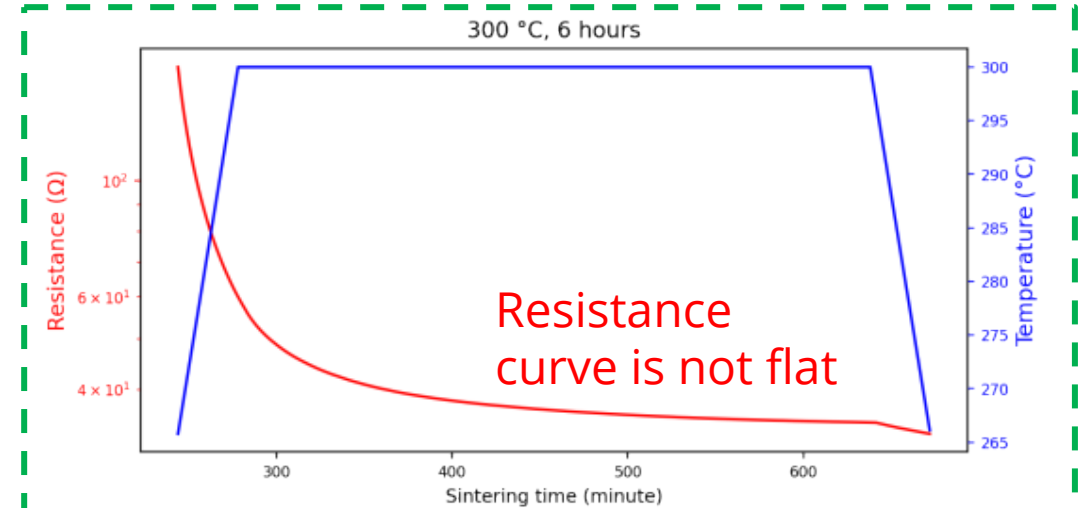
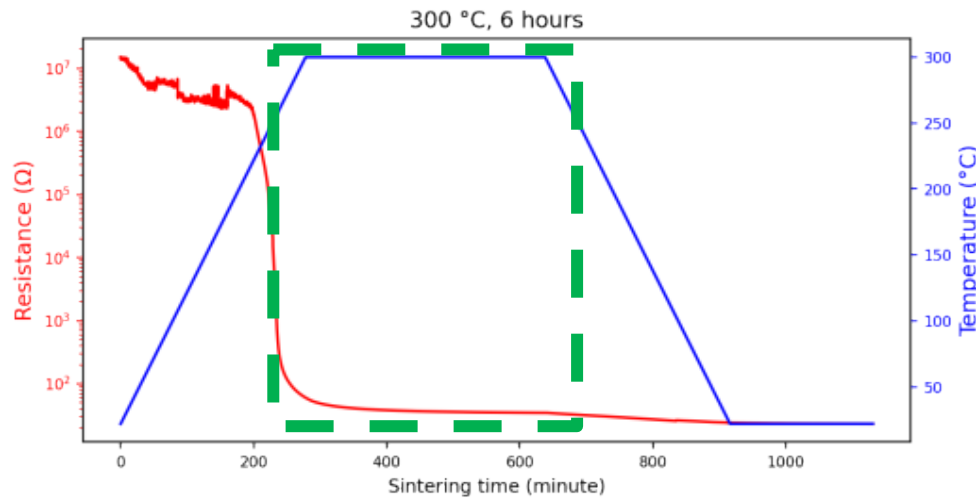


- UTDots Au40X showed the best performance
- Test data collected on *ultrasonic atomization*-based aerosol jet printers

	UTDots Au40X	UTDots Au25X	NC Au 25%
Line resolution	+	-	+
Infill quality	+	-	++
Deposition rate stability	++	+	-
Atomization stability	++	+	-
% bulk Au conductivity	30.8%	17.1%	28.1%
Price (per gram of Au)	\$446	\$466	\$571
Shelf-life	3 months	3 months	2 weeks
Storage condition	Ambient	Ambient	Fridge

# In-situ Resistance Monitoring while Sintering

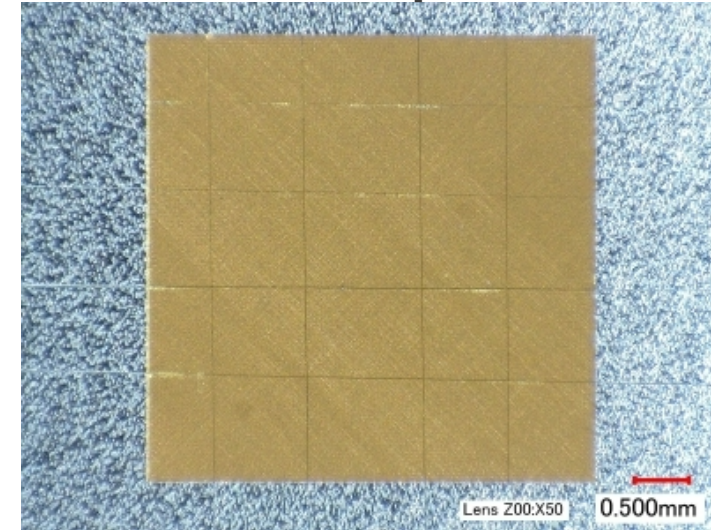
- Sintering for 6 and 9 hours at 300 °C
- Final resistivity  $0.050 \Omega \cdot \mu\text{m}$  after 9 hours at 300 °C
- 44% bulk Au conductivity



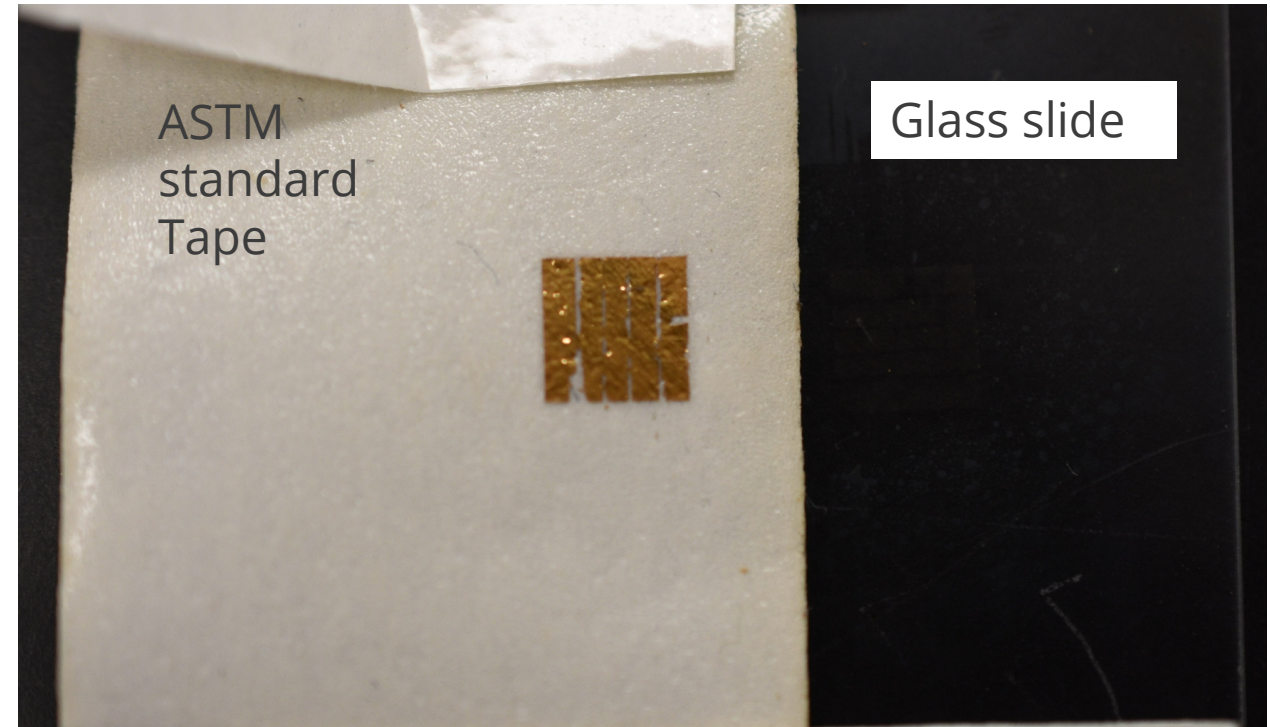
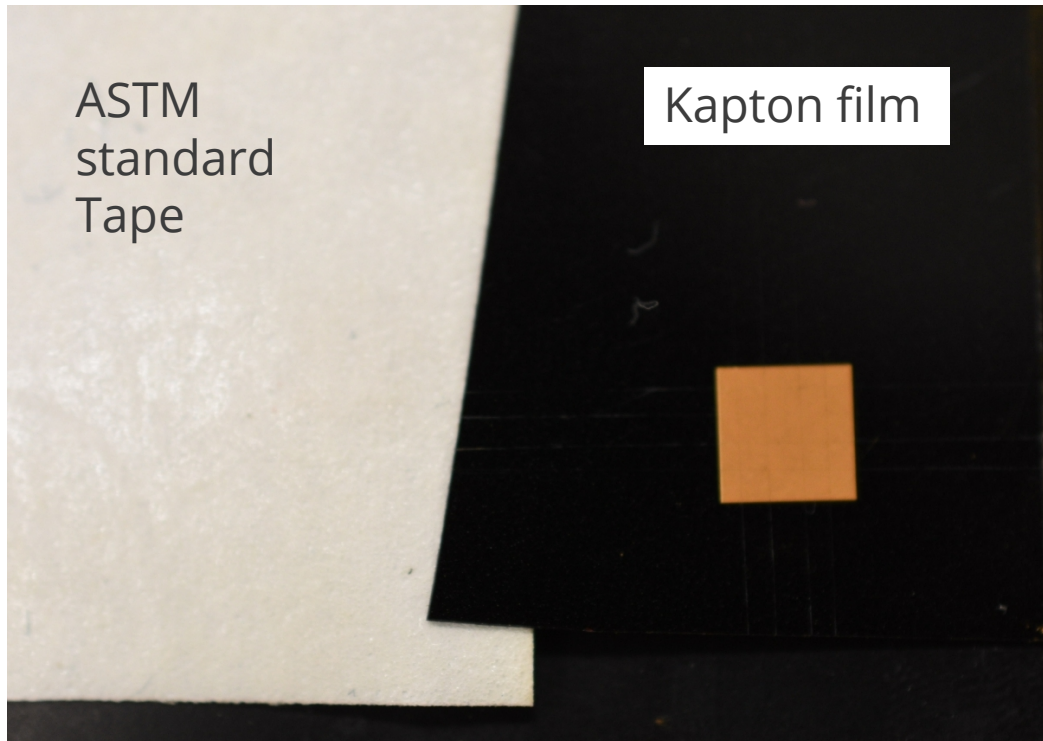
# Adhesion Test

- ASTM D3359-17
- Printed Au pad cross-cut
- Rating 5B for printing on Kapton film
- Rating 0B for printing on glass slide

Before Tape Test



Post Tape Test





# Conclusion



- UTDots Au40X out of the three inks has the best overall performance for ultrasonic atomization-based aerosol jet printing
  - High resolution (~30  $\mu\text{m}$  line width)
  - Good stability and long shelf life
  - High electrical conductivity
- 44% bulk Au conductivity after sintering at 300 °C for 9 hours
- A promising technique for making interconnects, high-frequency circuits, etc. at chip level, especially for harsh environment applications

## Disclaimer of endorsement:

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## Acknowledgements:

This work was funded by Sandia National Laboratories. *Sandia National Laboratories is a multimission laboratory managed and operated by National Technology & Engineering Solutions of Sandia, LLC, a wholly owned subsidiary of Honeywell International Inc., for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-NA0003525.*